



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1512-02 DATE: 29-Jan-2016 Product Affected: VFQFPN-132 Refer to Attachment II for the affected part numbers Date Effective: 29-Apr-2016	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark Lot # will have: <input checked="" type="checkbox"/> Back Mark "AS" prefix for UTAC, Thailand <input type="checkbox"/> Date Code <input type="checkbox"/> Other
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Contact: IDT PCN DESK E-mail: pcndesk@idt.com	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Please contact your local sales representative for sample request.
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology <input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Assembly Process <input type="checkbox"/> Equipment <input type="checkbox"/> Material <input type="checkbox"/> Testing <input checked="" type="checkbox"/> Manufacturing Site <input type="checkbox"/> Data Sheet <input type="checkbox"/> Other	<p>This notification is to advise our customers that IDT is transferring the affected products assembled at Amkor, Korea , K1 (ATK) to Amkor, China (ATC) as ATK will shutdown K1.</p> <p>There is no change to the moisture performance.</p> <p>Attachment I details the qualification results and Attachment II shows the affected list of part numbers.</p>
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RELIABILITY/QUALIFICATION SUMMARY:
Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ Name/Date: _____ Title: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i> E-Mail Address: _____ Phone# /Fax# : _____
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CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ **DATE:** _____



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ATTACHMENT I - PCN # : A1512-02

PCN Type: Manufacturing Site - Transfer Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is transferring the affected products assembled at Amkor, Korea, K1 (ATK) to Amkor, China (ATC) as ATK will shutdown K1.

The material set details of the current and new assembly location is as shown in Table 1. There is no change from the existing qualified lead frame material, lead finish, die attach, mold compound and wire for the new assembly location.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and New Assembly Location

	Existing Assembly (ATK, Amkor Korea)	New Assembly (ATC, Amkor China)
Die Attach	CRM1085A	CRM1085A
Wire	Au wire	Au wire
Mold Compound	G700	G700



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ATTACHMENT I - PCN # : A1512-02

Qualification Information and Qualification Data:

Affected Packages: VFQFPN-132

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: VFQFPN-132

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
Lead Integrity	JESD22-B105	0/3	0/3	0/3
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Bond Shear Test	JESD22-B116	0/5	0/5	0/5
Bond Pull Strength Test	Mils-Std-883, M2011	0/5	0/5	0/5
Solderability Test	JESD22-B102	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	-

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



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ATTACHMENT II - PCN # : A1512-02

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
89HMPEB383ZANQG	89HPES3T3ZBNQG8	89HMPEB383ZANQG8	89HMPEB383ZBNQGI8
89HPEB383ZBNQG	89HPES3T3ZBNQGI	89HMPEB383ZANQGI	89HPEB383ZANQG
89HPEB383ZBNQG8	89HPES3T3ZBNQGI8	89HMPEB383ZANQGI8	89HPEB383ZANQG8
89HPEB383ZBNQGI	89HPES4T4ZBNQG	89HMPEB383ZBNQG	89HPES4T4ZBNQG8
89HPEB383ZBNQGI8	89HPEB383ZANQGI8	89HMPEB383ZBNQG8	
89HPES3T3ZBNQG	89HPEB383ZANQGI	89HMPEB383ZBNQGI	